

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China









Product Guide



HD_1105W Series, Dome Lens Type InGaN/SiC SMT LED

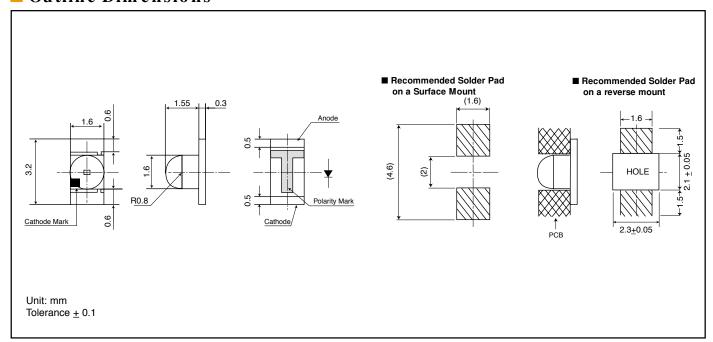
Features

- · High brightness (InGaN/SiC) die material
- Available in green (525nm), bluish-green (505nm) and blue (470nm) colors
- · Reflow and dip soldering compatible
- · Available for both standard and reverse mounting
- 1000V minimum ESD protection

Applications

- · Automotive indicator display
- · Various other backlight uses

Outline Dimensions



Electro-Optical Characteristics

(Ta=25°C)

Part No.	Material	Emitted Color	Lens Color	Luminous Intensity _V		Wavelength Spectral Line Peak Dominant Half Width				Forward Voltage v₅			Reverse Current _{IR}		Viewing Angle	
				MIN.	TYP.	İF	λρ TYP.	λd TYP.	Δλ TYP.	lF	TYP.	MAX.	lF	MAX.	V R	(2 0 1/2)
HDG1105W	InGaN/SiC	Green	Water Clear	70	140	10	522	525	30	10	3.3	3.8	10	100	5	40°
HDC1105W	InGaN/SiC	Bluish-Green		70	140	10	502	505	30	10	3.3	3.8	10	100	5	
HDB1105W	InGaN/SiC	Blue		35	70	10	467	470	26	10	3.3	3.8	10	100	5	
	Units				mcd		nm			mA	V mA		μΑ	٧	Deg.	

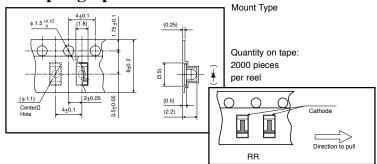
Absolute Maximum Ratings

(Ta=25°C)

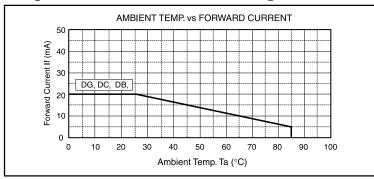
Item		Green	Bluish-Green	Blue	Units			
Item	Symbol	HDG	HDC	HDB				
Power Dissipation	Pd	76	76	76	mW			
Forward Current	 F	20	20	20	mA			
Peak Forward Current	I _{FM}	48	48	48	mA			
Reverse Voltage	VR	5	5	5	٧			
Operating Temperature	Topr	-40 to +85						
Storage Temperature	Tstg	-40 to +100						
Derating*	ΔI _F	0.28 (DC) 0.69 (Pulse)						

^{*} Ta=25°C, I_{FM} applies for the pulse width ≤ 1msec. and duty cycle ≤1/20.

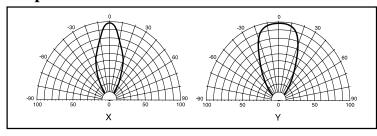
■ Taping Specifications for Reverse



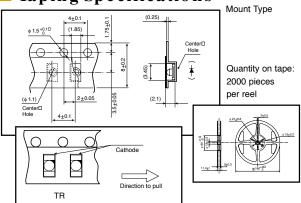
Operation Current Derating Chart (DC)



Spatial Distribution



Taping Specifications for Standa

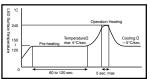


Precautions

Please follow these handling precautions to prevent damage to the chip and ensure its reliability.

1. Soldering conditions:

- <u>Soldering iron</u>: Temperature at tip of iron: 280°C max. (30W max.) Soldering time: 3 sec. max.
- <u>Dip soldering</u>: Preheating: 120 ~ 150°C max. (resin surface temp.)
 60 ~ 120 sec. max. Bath temperature: 260°C max. Dipping Time: 5 sec. max.
- Reflow Soldering:



2. Cleaning:

- If cleaning is required, use the following solutions for less than 1 minute, at less than 40°C.
- Appropriate chemicals: Ethyl alcohol and isopropyl alcohol.
- Effect of ultrasonic cleaning on the LED resin body differs depending on such factors as the oscillator output, size of PCB and LED mounting method. The use of ultrasonic cleaning should be enforced at proper output after confirming there is no problem.

Product specifications subject to change without notice. PGHD1105W-0301

